ON Semiconductor

Is Now



To learn more about onsemi[™], please visit our website at www.onsemi.com

onsemi and Onsemi. and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. onsemi reserves the right to make changes at any time to any products or information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/ or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use onsemi products for any such unintended or unauthorized application,

SC75 Dual Common Anode Zener for ESD Protection

This dual monolithic silicon voltage suppressor is designed for applications requiring transient overvoltage protection capability. It is intended for use in voltage and ESD sensitive equipment such as computers, printers, business machines, communication systems, medical equipment, and other applications. Its dual junction common anode design protects four separate lines using only one package.

These devices are ideal for situations where board space is at a premium.

Specification Features

- SC-75 Package Allows Two Separate Unidirectional Configurations
- Low Leakage < 1 μA @ 3 V
- Breakdown Voltage: 5.3 5.9 V @ 1 mA
- Low Capacitance (40 pF typical between terminals)
- ESD Protection Meeting IEC61000-4-2
- Pb-Free Package is Available

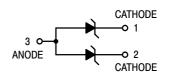
Mechanical Characteristics

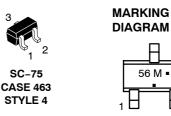
- Void Free, Transfer-Molded, Thermosetting Plastic Case
- Corrosion Resistant Finish, Easily Solderable
- Package Designed for Optimal Automated Board Assembly
- Small Package Size for High Density Applications



ON Semiconductor®

http://onsemi.com





56 = Device Code

M = Date Code*

■ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
NZL5V6ATT1	SC-75	3000/Tape & Reel
NZL5V6ATT1G	SC-75 (Pb-Free)	3000/Tape & Reel

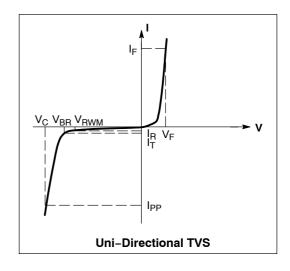
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS

(T_A = 25°C unless otherwise noted)

UNIDIRECTIONAL (Circuit tied to Pins 1 and 3, or 2 and 3)

Symbol	Parameter
I _{PP}	Maximum Reverse Peak Pulse Current
V _C	Clamping Voltage @ I _{PP}
V _{RWM}	Working Peak Reverse Voltage
I _R	Maximum Reverse Leakage Current @ V _{RWM}
V _{BR}	Breakdown Voltage @ I _T
I _T	Test Current
ΘV _{BR}	Maximum Temperature Coefficient of V _{BR}
I _F	Forward Current
V _F	Forward Voltage @ I _F
Z _{ZT}	Maximum Zener Impedance @ I _{ZT}
I _{ZK}	Reverse Current
Z _{ZK}	Maximum Zener Impedance @ I _{ZK}



MAXIMUM RATINGS ($T_A = 25^{\circ}C$ unless otherwise noted)

	Characteristic	Symbol	Value	Unit	
Steady State Power - 1	Diode (Note 1)	P _D	150	mW	
Maximum Junction Ten	nperature	T _{Jmax}	150	°C	
Operating Junction and	Storage Temperature Range	T _J T _{stg}	T _J T _{stg} –55 to +150		
ESD Discharge	IEC61000-4-2, Air Discharge IEC61000-4-2, Contact Discharge	V _{PP}	±15 ±8	kV	
Lead Solder Temperature (10 seconds duration)		T _L	260	°C	

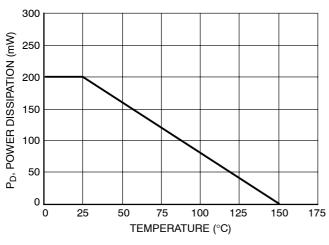
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

ELECTRICAL CHARACTERISTICS

	Breakdown Voltage V _{BR} @ 1 mA (V)		Leakage Current I _{RM} @ V _{RM} = 3.0 V	V _C @ I _{PP} (Note 2)		Typical Capacitance @ 0 V Bias @ 1 MHz	Max V _F @ I _F = 10 mA	
Device	Min	Nom	Max	(μΑ)	V _C (V)	I _{PP} (A)	(pF)	(V)
NZL5V6	5.3	5.6	5.9	1.0	9.97	6.11	40	1.25

^{2.} Surge current waveform per Figure 2 and clamping voltage (V_C) per Figure 6.

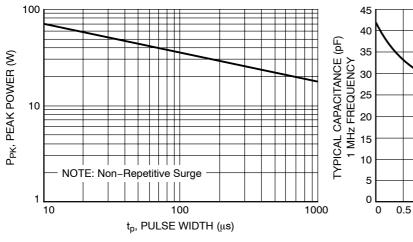
^{1.} Only 1 diode under power. For all 4 diodes under power, P_D will be 25%. Mounted on FR-4 board with min pad.



100 PEAK VALUE $I_{RSM} \ @ \ 8 \ \mu s$ OF PEAK PULSE CURRENT PULSE WIDTH (tp) IS DEFINED 80 AS THAT POINT WHERE THE 70 PEAK CURRENT DECAY = 8 μs 60 HALF VALUE $I_{\mbox{\scriptsize RSM}}/2\ \mbox{\Large @}\ 20\ \mu \mbox{\scriptsize s}$ 50 40 30 20 10 0 20 40 60 0 80 t, TIME (μs)

Figure 1. Steady State Power Derating Curve

Figure 2. 8 X 20 µs Pulse Waveform



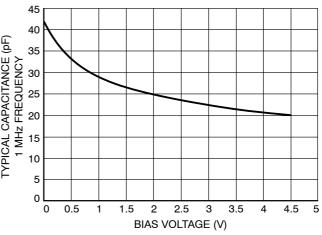
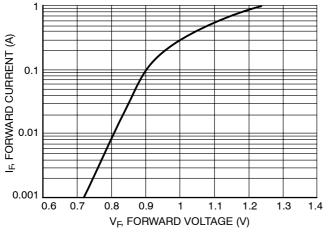


Figure 3. Pulse Rating Curve

Figure 4. Capacitance



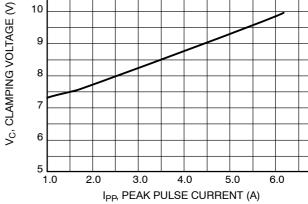


Figure 5. Forward Current versus **Forward Voltage**

Figure 6. Clamping Voltage versus Peak Pulse Current (8 x 20 µs Pulse)

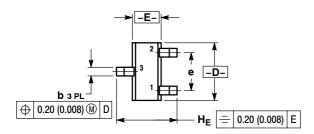
7.0

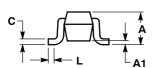
11

10

PACKAGE DIMENSIONS

SC-75/SOT-416 CASE 463-01 ISSUE F





NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
 Y14.5M. 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER.

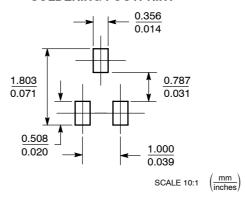
	MIL	LIMETE	ERS	INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.70	0.80	0.90	0.027	0.031	0.035
A1	0.00	0.05	0.10	0.000	0.002	0.004
b	0.15	0.20	0.30	0.006	0.008	0.012
С	0.10	0.15	0.25	0.004	0.006	0.010
D	1.55	1.60	1.65	0.059	0.063	0.067
E	0.70	0.80	0.90	0.027	0.031	0.035
е	1	.00 BSC)	0.04 BSC		
L	0.10	0.15	0.20	0.004	0.006	0.008
HE	1.50	1.60	1.70	0.061	0.063	0.065

STYLE 4:

PIN 1. CATHODE 2. CATHODE

2. CATHODE

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA **Phone**: 303–675–2175 or 800–344–3860 Toll Free USA/Canada

Fax: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center

Phone: 81-3-5773-3850

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

NZL5V6ATT1/D